CLAIMS

1. A thermosetting sealing resin sheet, having a thickness t [mm] and a storage modulus G′ [Pa] at 50°C, wherein the product α of t and G′ satisfies the following expression 1:

expression 1: $300 \leq \alpha \leq 1.5 \times 10^5$.

2. A sealing sheet with a separator, comprising the sealing resin sheet recited in claim 1, and the separator which is stacked over at least one surface of the sealing resin sheet, and

having a bend elastic constant E [N/mm^2] at 25°C; the sealing resin sheet having an area A [mm^2]; wherein the product β of E and A satisfies the following expression 2:

expression 2: $4.0 \times 10^6 \leq \beta \leq 1.7 \times 10^9$.

3. A semiconductor device, produced using the sealing resin sheet recited in claim 1.

4. A semiconductor device, produced using the sealing sheet with the separator that is recited in claim 2.

5. The sealing resin sheet according to claim 1, the area A thereof being 40000 mm^2 or more.

6. The sealing sheet with the separator according to claim 2, the area A of the sealing resin sheet being 40000 mm^2 or more.

7. A production method for a semiconductor device, comprising:

step A of providing a stacked body comprising a support and one or more semiconductor chips fixed onto the support,

step B of providing the sealing sheet with the separator that is recited in claim 2,

step C of arranging the sealing sheet with the separator over the semiconductor chip(s) of the stacked body, and

step D of burying the semiconductor chip(s) into the sealing resin sheet to form a sealed body in which the semiconductor chip(s) is/are buried in the sealing resin sheet.